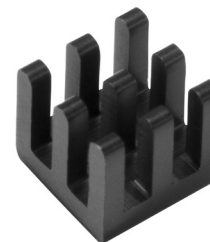




**MODEL:** HSB01-080808 | **DESCRIPTION:** HEAT SINK

**FEATURES**

- BGA design
- small footprint
- aluminum alloy
- black anodized finish



**MODEL**

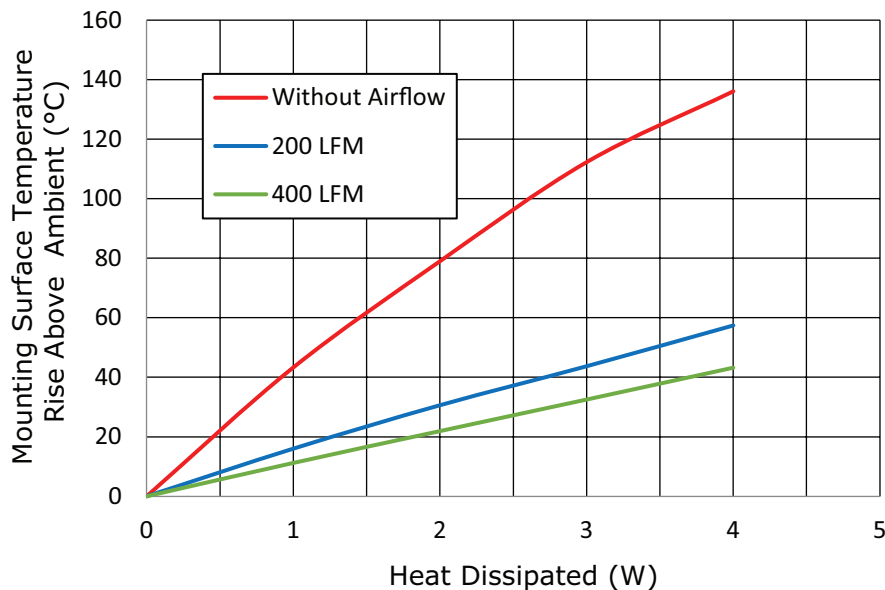
HSB01-080808	thermal resistance <sup>1</sup>			power dissipation <sup>1</sup> @ 75°C ΔT, nat conv [W]
	@ 75°C ΔT, nat conv [°C/W]	@ 1 W, nat conv [°C/W]	@ 1 W, 200 LFM [°C/W]	
	39.10	43.30	16.00	11.20

Note: 1. See performance curves for full thermal resistance details.

**PERFORMANCE CURVES**

Power (W)	Heatsink Temperature Rise Above Ambient (ΔT = T <sub>hs</sub> - T <sub>a</sub> ) [°C]		
	Natural Conv.	200 LFM	400 LFM
0	0	0	0
1	43.3	16.0	11.2
2	79.0	30.6	21.9
3	112.3	43.7	32.5
4	136.1	57.4	43.2

T<sub>hs</sub>: "hot spot" temperature measured on the heatsink  
T<sub>a</sub>: ambient temperature



**CUI DEVICES** | **MODEL:** HSB01-080808 | **DESCRIPTION:** HEAT SINK

## MECHANICAL DRAWING

units: mm  
tolerance:  $\pm 0.38$  mm

MATERIAL	AL 6063-T5
FINISH	black anodized
WEIGHT	1.9 g

